

Examiner-Initiated Interview Summary

Application No.

09/940,855

Applicant(s)

NAMBA, KAZUYOSHI

Examiner

Mark Spisich

Art Unit

1744

All Participants:

(1) Mark Spisich.

(2) Michael Makuch (Appl Rep).

Status of Application: _____

(3) _____.

(4) _____.

Date of Interview: 8 November 2004

Time: _____

Type of Interview:

☒ Telephonic

☐ Video Conference

☐ Personal (Copy given to: ☐ Applicant ☐ Applicant's representative)

Exhibit Shown or Demonstrated: ☐ Yes ☐ No

If Yes, provide a brief description:

Part I.

Rejection(s) discussed:

102(e) based on Nishimura et al (USP 6,286,525)

Claims discussed:

4 and 7

Prior art documents discussed:

Nishimura et al (USP 6,286,525)

Part II.

SUBSTANCE OF INTERVIEW DESCRIBING THE GENERAL NATURE OF WHAT WAS DISCUSSED:

See Continuation Sheet.

Part III.

- ☒ It is not necessary for applicant to provide a separate record of the substance of the interview, since the interview directly resulted in the allowance of the application. The examiner will provide a written summary of the substance of the interview in the Notice of Allowability.
- ☐ It is not necessary for applicant to provide a separate record of the substance of the interview, since the interview did not result in resolution of all issues. A brief summary by the examiner appears in Part II above.


(Examiner/SPE Signature)

(Applicant/Applicant's Representative Signature – if appropriate)

Continuation of Substance of Interview including description of the general nature of what was discussed: Applicant had amended claims 4 and 7 by reciting that the first and second scrub heads each passed through the rotation center of the wafer and moved toward the periphery thereof. Although the prior art ('525) fails to disclose the scrub heads doing this during cleaning of the wafer, they do each pass through the center as they move FROM the cleaning position TO the rest position (see fig 8B). The examiner proposed amending claims 4 and 7 to clarify that each of the scrub heads passes through the rotation center while they are cleaning the wafer..